Qualitek 619D No Clean Dispensing Solder Paste

SKU: 390-619D | Sizes: Sn62 Type 3 - 35gm Syringe, Sn62 Type 3 - 100gm Syringe, Sn62 Type 4 - 35gm Syringe, Sn62 Type 4 - 100gm Syringe

Features & Benefits

- **Alloy composition**: 62% Tin, 36% Lead, 2% Silver
- **Metal content**: 88% for superior soldering performance
- **No Clean flux** (ROL0) for minimal residue and easy cleaning
- **Bellcore compliant** for high industry standards
- **Excellent dot-to-dot consistency** for precise applications
- **Non-corrosive** for safe use
- **Excellent wettability** for smooth, reliable soldering
- **Pin-testable post-solder residue** for quality assurance
- **Type 3** (for 0.5 mm pitch or above) and **Type 4** (for fine-pitch below 0.5 mm) options available

About the Qualitek 619D No Clean Dispensing Solder Paste

Qualitek 619D No Clean Dispensing Solder Paste is specifically designed for Surface Mount Technology (SMT) applications using a syringe dispensing method.
With a metal content of 88%, this paste is formulated with a tin (62%), lead (36%), and silver (2%) alloy, offering excellent wetting properties and dot-to-dot consistency for precise application.
Ideal for fine-pitch applications, it is available in Type 3 for pitches at or above 0.5 mm and Type 4 for fine-pitch applications below 0.5 mm.
The paste features a non-corrosive, no-clean flux (ROL0) that leaves minimal residue and is post-solder residue pin testable, making it ideal for high-quality, efficient soldering.

Specifications

Property	Detail
Application	ESD-protected areas, electronics mfg, cleanrooms